

SMAG Plastic-Encapsulate Diodes

Schottky Rectifier

Features

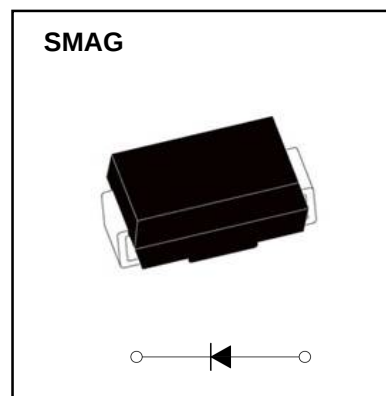
- I_o 2A
- V_{RRM} 100V
- High surge current capability
- Polarity: Color band denotes cathode
- Low V_f

Applications

- Rectifier

Marking

- SS210L



Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Conditions	SS210L
Repetitive Peak Reverse Voltage	V_{RRM}	V		100
Maximum RMS Voltage	V_{RMS}	V		70
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave, Resistance load, $T_L=125^{\circ}C$	2.0
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave,1 cycle, $T_a=25^{\circ}C$	70
Junction Temperature	T_J	$^{\circ}C$		-55~+150
Storage Temperature	T_{STG}	$^{\circ}C$		-55~+150

Electrical Characteristics ($T_a=25^{\circ}C$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition		SS210L	
Peak Forward Voltage	V _F	V	IF=1A	Ta=25℃	0.66(TYP)	0.70(MAX)
			IF=2A		0.71(TYP)	0.75(MAX)
Peak Reverse Current	I _{RRM1}	mA	V _{RM} =V _{RRM}	Ta=25℃	0.01(MAX)	
	Ta=70℃			0.015(MAX)		
	I _{RRM2}			Ta=100℃	5(MAX)	
Thermal Resistance(Typical)	R _{θJ-A}	℃/W	Between junction and ambient		55	
	R _{θJ-L}		Between junction and lead		17	

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

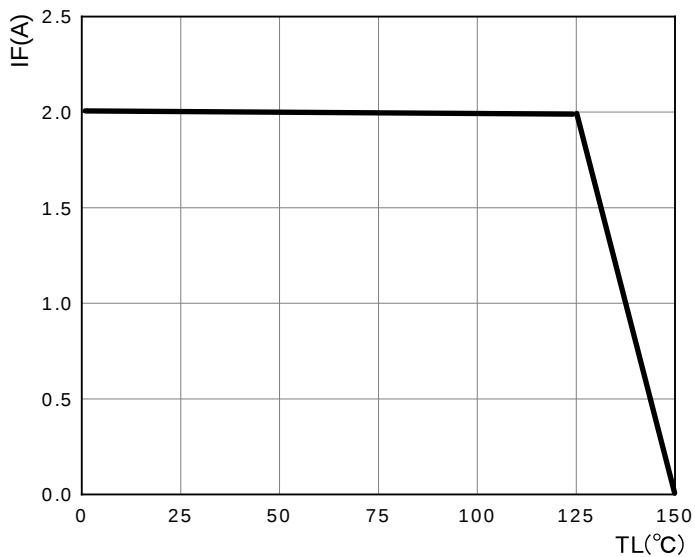


FIG 2: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

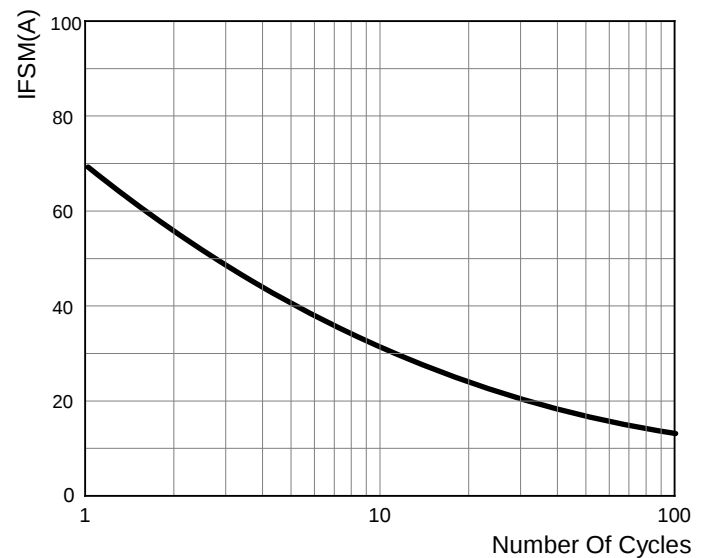


FIG.3: TYPICAL FORWARD CHARACTERISTICS

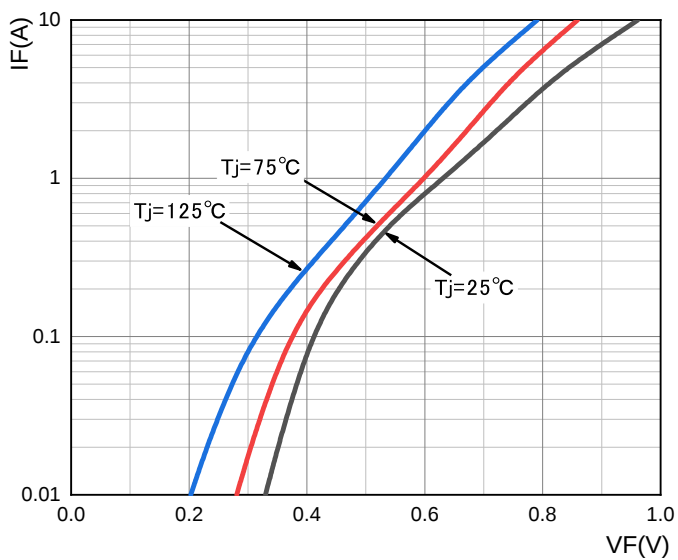
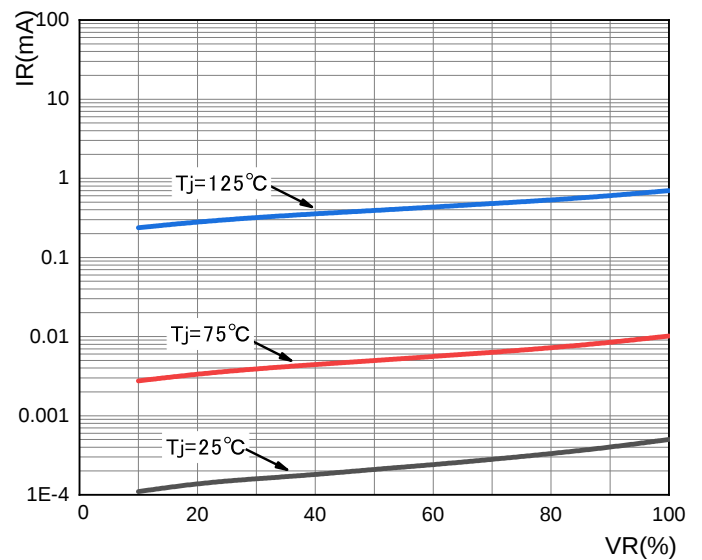
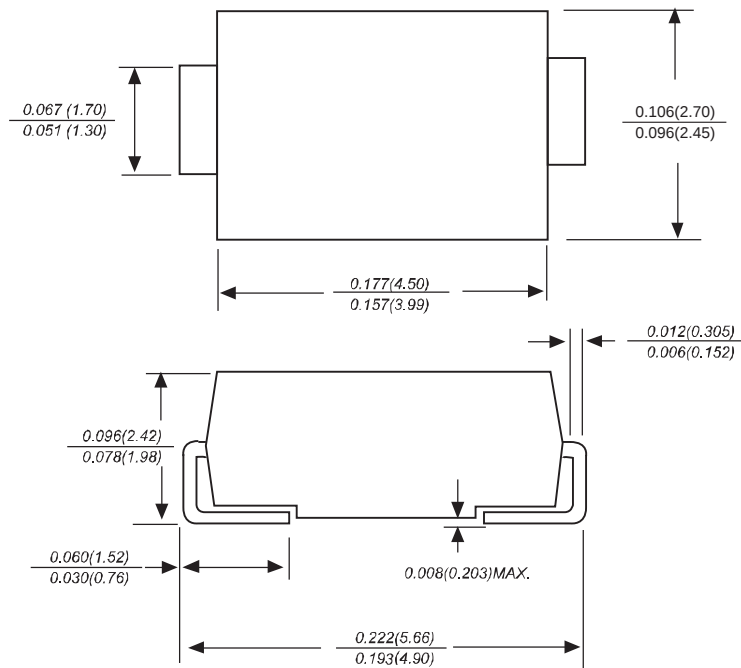


FIG.4: TYPICAL REVERSE CHARACTERISTICS

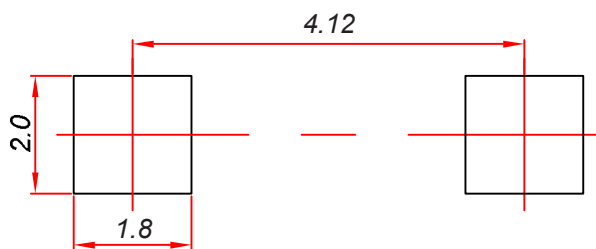


SMAG Package Outline Dimensions



Dimensions in inches and (millimeters)

SMAG Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

NOTICE

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Reel Taping Specifications For Surface Mount Devices–SMAG



FIG:CONFIGURATION OF AXIAL TAPING

ITEM	SYMBOL	SMAG mm(inch)
Carrier width	A	2.79±0.1(0.110±0.004)
Carrier length	B	5.33±0.1(0.210±0.004)
Carrier depth	C	2.36±0.1(0.093±0.004)
Sprocket hole	d	1.5±0.05(0.059±0.0002)
Reel outside diameter	D	330/178±2.0(13/7.0±0.79)
Reel inner diameter	D1	8.0±0.2(0.315±0.008)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Sprocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Total tape thickness	T	0.28±0.02(0.011 ±0.0008)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE:Devices are packde in accordance with EIA standard RS-481-A and specification given above.